

MATERIAL DECLARATION SHEET



Material Number	CRF0805 Series (Cu)			
Product Line	Metal Plate Current Sensing Chip Resistors			
Compliance Date	2022/12/21			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Protective Coating	Epoxy	0.00085	Epoxy	29690-82-2	100 %	0.00085	15.39%
2	Resistive Body	Metal	0.0032	Copper	7440-50-8	100 %	0.003209	58.36%
3	Marking Layer	Epoxy	0.000003	Epoxy	29690-82-2	100 %	0.000003	0.06%
4	Cu Plating	Metal	0.0012	Copper(II) oxide	1317-38-0	100 %	0.0012	22.71%
5	Ni Plating	Metal	0.0001	Nickel	7440-02-0	100 %	0.0001	1.84%
6	Sn Plating	Metal	0.0001	Tin	7440-31-5	100 %	0.0001	1.64%
Total weight			0.0055					

This Document was updated on: 2022/12/21

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.